\* PALM INTRANET

Day: Thursday Date: 12/21/2006

Time: 14:41:07

## **Inventor Information for 10/749359**

Inventor Name	City	State/Country
SAUCIUC, IOAN	PHOENIX	ARIZONA
CHRYSLER, GREGORY M.	CHANDLER	ARIZONA
Appln Info Contents Petition Info	Atty/Agent Info	ontinuity/Reexam Fore
	A SANCTON OF THE PARTY AND ASSESSMENT OF THE PARTY AS	ontinuity/Reexam Fore
Search Another: Application#	Search or Pate	
Search Another: Application#		nt# Search
Search Another: Application#	Search or Pate Search or PG PUE	nt# Search

To go back use Back button on your browser toolbar.

Back to PALM | ASSIGNMENT | OASIS | Home page

1	US 7098079 B2	20060829	Electronic assembly with high capacity thermal interface and methods of manufacture	438/122	257/E23.101; 257/E23.111; 257/E31.131	Chrysler; Gregory M. et al.
1	US 7082031 B2	20060725	Heatsink device and method	361/700	165/104.33; 257/E23.088; 257/E23.099; 361/703; 62/259.2; 62/3.2	Leija; Javie et al.
1	US 7071552 B2	20060704	IC die with directly bonded liquid cooling device	257/712	257/714; 257/E23.098	Ravi; Kramadhati V. et al.
1	US 7063268 B2	20060620	Electro-active fluid cooling system	236/93R	137/67; 236/93A; 251/129.01; 310/365; 361/699; 417/413.1; 62/259.2	Chrysler; Gregory M et al.
1	US 7034394 B2	20060425	Microelectronic assembly having thermoelectric elements to cool a die and a method of making the same	257/712	257/720; 257/E21.508; 257/E23.079; 257/E23.082; 257/E27.008	Ramanatha Shriram et al.
1	US 7031155 B2	20060418	Electronic thermal management	361/695	257/722; 257/E23.099; 361/697	Sauciuc; Ioan et al.
1	US 7021891 B2	20060404	Micro-impeller miniature centrifugal compressor	415/98	361/695; 415/203; 416/183; 416/184; 416/185	Sanchez; Eduardo A. et al.
1	US 7012011 B2	20060314	Wafer-level diamond spreader	438/455	438/105	Chrysler; Gregory M et al.
1	US 6992382 B2	20060131	Integrated micro channels and manifold/plenum using separate silicon or low-	257/717	257/706; 257/708; 257/712; 257/713; 257/714;	Chrysler; Gregory M et al.

•			•			
	US	20060124	cost polycrystalline silicon	165/48.1	257/715; 257/716; 257/718; 257/E23.098; 361/676; 361/687; 361/689; 361/703 165/80.2;	Chrysler;
1	6988531 B2	20000124	Micro-chimney and thermosiphon die-level cooling	103/48.1	165/905; 165/905; 257/E23.087; 257/E23.088	Gregory M. et al.
1	US 6981380 B2	20060103	Thermoelectric cooling for microelectronic packages and dice	62/3.2	257/E23.082; 62/259.2; 62/3.7	Chrysler; Gregory M. et al.
1	US 6971442 B2	20051206	Method and apparatus for dissipating heat from an electronic device	165/104.25	165/104.21; 165/104.26; 165/104.33; 257/714; 257/715; 257/E23.088; 361/700	Sauciuc; Ioan et al.
1	US 6967840 B2	20051122	Clearing of vapor lock in a microchannel cooling subsystem	361/699	165/80.4; 174/15.1; 257/714; 257/E23.098; 361/700	Chrysler; Gregory M. et al.
1	US 6936497 B2	20050830	Method of forming electronic dies wherein each die has a layer of solid diamond	438/105	148/DIG.12; 257/E21.122; 257/E23.111; 257/E25.013; 257/E29.082; 438/459; 438/519; 438/977	
1	US 6921706 B2	20050726	Electronic assembly including a die having an integrated circuit and a layer of diamond to transfer heat	438/460	257/E21.122; 257/E21.568; 257/E23.111; 438/113	Chrysler; Gregory M. et al.
1	US	20050712	Apparatus and	361/700	165/104.26;	Erturk;

			•			
	6917522		method for		165/104.33;	Hakan et al.
	B1	:	cooling		165/80.4;	
			integrated circuit		174/15.2;	
			devices		257/715;	
					257/E23.088;	
					361/695;	
					361/697;	
				13.0	361/699;	
1	US	20050322	Heat mine having	165/104.26	62/259.4	Chau; David
1	6868898	20030322	Heat pipe having	103/104.20	174/15.2;	S. et al.
	B2		an inner retaining wall for wicking	•	361/700	S. et al.
	DZ		components		3017700	
1	US	20050301	Composite fins	361/704	165/185;	Chrysler;
*	6862183	20030301	for heat sinks	3017701	165/80.3;	Gregory M.
	B2		101 Hour billies		174/16.3;	et al.
					257/722;	
			•		257/E23.103;	
			•		29/890.03;	
					361/709;	
					361/719	
1	US	20050125	Phase-change	62/3.7	165/104.21;	Sauciuc;
.	6845622		refrigeration		62/3.2	Ioan et al.
	B2		apparatus with			
			thermoelectric			
			cooling element			
1	US	20040921	and methods  Method and	361/687	361/704;	Pokharna;
	6795311	20040921	apparatus for	3017087	710/303;	Himanshu et
	B2		cooling portable		710/304	al.
	52		computers		710/50	
1	US	20040831	Embedded liquid	361/699	165/80.4;	Maveety;
	6785134		pump and		257/714;	James G. et
	B2		microchannel		257/715;	al.
			cooling system		257/E23.087;	
					257/E23.098;	
					361/689;	
		•			361/698;	
<u>_</u>	TIC	20040000	F1	0.57/707	361/700	C1 1
1	US	20040803	Electronic	257/706	257/E21.122;	Chrysler;
	6770966	_	assembly		257/E21.568; 257/E23.111	Gregory M. et al.
	B2	,	including a die		231/E23.111	ciai.
			having an integrated circuit			
			and a layer of			
1	1 :	1	LABO A TAVELOI		1	

					•		
			·				•
			transfer heat				
1	US	20040316	Electronic	438/125	257/E23.101;	Mahajan;	
	6706562		assembly with		257/E23.111;	Ravi V. et	
	B2		high capacity		438/122	al.	
			thermal spreader	· .			
		•	and methods of	,	!	·	
			manufacture				
1	US	20031209	Integrated vapor	361/700 ·	165/104.26;	Prasher;	
1	6661660	20031207	chamber heat	301,700	165/80.3;	Ravi et al.	
	B2		sink and spreader		165/80.4;	Tavi vi ai.	
	DZ	!	and an embedded		174/15.2;		
			direct heat pipe		174/15.2,		
			attachment		257/714;		
			attachhient		257/718;		
					257/E23.088;		]
		·			361/702;		
					361/703;		
					361/704;		ľ
			,		361/717;		
					361/718;		
					361/719		ļ.
1	US	20031125	Electronic	257/704	257/712;	Chrysler;	
	6653730		assembly with		257/713;	Gregory M.	
	B2		high capacity		257/E23.101;	et al.	
			thermal interface		257/E23.111		
1	US	20031118	Piezoelectric	361/699	165/104.33;	Chrysler;	
	6650542		actuated jet		165/80.4;	Gregory M.	
	B1		impingement		174/15.1;	et al.	
		İ	cooling		257/714;		
					257/E23.1;		
					361/698;		
					361/704		
1	US ·	20031111	Mobile computer	361/687	62/3.2	Pokharna;	
	6646874		system with	,	:	Himanshu et	
	B2		detachable		·	al.	
	,		thermoelectric				
			module for				
			enhanced cooling	·			
			capability in a				
			docking station				
1	US	20031028	Integrated vapor	361/700	165/80.4;	Prasher;	1
•	6639799	200310-0	chamber heat	301,.01	174/15.2;	Ravi et al.	
	B2		sink and spreader		257/714;		
	52		and an embedded		257/715;		
			direct heat pipe		257/E23.088;		,
			attachment		361/203;		

.

				•				
ſ						361/699	·	•
	1	US 6636423 B2	20031021	Composite fins for heat sinks	361/703	165/185; 257/722; 257/E23.103; 29/890.03	Rinella; Agostino C. et al.	
	1	US 6609561 B2	20030826	Tunnel-phase change heat exchanger	165/104.33	165/104.21; 165/80.4; 174/15.2; 257/715; 257/E23.088;	Sauciuc; Ioan et al.	
-	1	US 6561267 B2	20030513	Heat sink and electronic circuit module including the same	165/185	361/700 165/80.3; 174/16.3; 257/722; 257/E23.103; 257/E23.105; 361/695; 361/704	Sauciuc; Ioan et al.	
	1	US 6549407 B1	20030415	Heat exchanger retention mechanism	361/699	165/80.4; 174/15.1; 257/714; 257/E23.094; 257/E23.098; 257/E23.104; 361/698; 361/701; 361/702; 361/719	Sauciuc; Ioan et al.	
	1	US 6223813 B1	20010501	Ultra high- density, high- performance heat sink	165/185	165/80.3; 174/16.3; 257/722; 257/E23.105; 29/890.03; 361/703	Chrysler; Gregory Martin et al.	
	1	US 6223810 B1	20010501	Extended air cooling with heat loop for dense or compact configurations of electronic components	165/104.33	165/104.26; 257/715; 257/E23.099; 361/700	Chu; Richard C. et al.	·
	1	US 6213194 B1	20010410	Hybrid cooling system for electronics module	165/80.3	165/80.4; 257/714; 257/722; 361/696;	Chrysler; Gregory M. et al.	

				<u> </u>	62/259.2	
1	US 6205796 B1	20010327	Sub-dew point cooling of electronic systems	62/94	361/700; 62/259.2	Chu; Richard C. et al.
1	US 6035655 A	20000314	Modular refrigeration system	62/259.2	62/196.4	Hare; Jeffrey J. et al.
1	US 6034872 A	20000307	Cooling computer systems	361/699	165/165; 165/170; 361/735; 62/259.2	Chrysler; Gregory M. et al.
1	US 6023410 A	20000208	Extended cooling for portable computers	361/681	361/687; 361/690; 361/707	Chu; Richard C. et al.
1	US 5970731 A	19991026	Modular refrigeration system	62/196.4	62/228.4	Hare; Jeffrey J. et al.
1	US 5963425 A	19991005	Combined air and refrigeration cooling for computer systems	361/695	165/104.33; 165/80.4; 174/15.1; 361/699; 454/186; 62/259.2	Chrysler; Gregory M. et al.
1	US 5954127 A	19990921	Cold plate for dual refrigeration system	165/170	165/164; 165/165; 361/700; 62/259.2	Chrysler; Gregory M. et al.
1	US 5953930 A	19990921	Evaporator for use in an extended air cooling system for electronic components	62/259.2	165/104.21; 165/104.33; 257/E23.088; 361/700	Chu; Richard C. et al.
1	US 5934364 A	19990810	Cold plate for dual refrigeration systems	165/170	165/164; 165/80.2	Chrysler; Gregory M et al.
1	US 5926368 A	19990720	Enhanced air cooling system with attached cooling unit	361/695		Chrysler; Gregory Martin et al.
1	US 5896922 A	19990427	Cold plate for dual refrigeration systems	165/165	165/146; 165/170; 62/259.2	Chrysler; Gregory M. et al.
1	US 5825620	19981020	Enhanced air cooling system	361/695		Chrysler; Gregory

		<u> </u>		T	<del></del>	Martin et al.
	A		with attached			Martin et al.
1	US	19980602	Cooling unit Orientation	361/700	165/104.26;	Anderson;
1	5761037	19980002	independent	301/700	165/80.4;	Timothy
	A		evaporator		257/E23.088;	Merrill et al.
*	Λ		Cvaporator		62/259.2	Wichin Ct ai.
1	US	19980602	Method of	29/890.03	257/E23.105;	Chrysler;
_	5758418		making an ultra		29/890.054	Gregory
	Α	•	high-density,			Martin et al.
		•	high-			
			performance heat			
		,	sink	·		
1	US	19980428	Method for field	454/184	361/695	Chrysler;
	5743794		upgrading of air			Gregory
	Α		cooling capacity			Martin et al.
1	US	19980217	Extended surface	361/704	174/16.3;	Agonafer;
ľ	5719745		cooling for chip		257/722;	Dereje et al.
	A		stack		257/E25.013;	
<u> </u>	***	10000106	applications	1.65/101	361/710	
1	US	19980106	Air flow	165/121	165/80.3;	Agonafer;
	5704419		distribution in		257/E23.099; 361/697	Dereje et al.
	A		integrated circuit spot coolers		3.01/09/	
1.	US	19970325	Enhanced flow	361/697	165/121;	Anderson;
I.	5615084	19970323	distributor for	301/07/	165/80.3;	Timothy M.
	A		integrated circuit		257/E23.099;	et al.
			spot coolers		361/719;	
			1		415/178;	
			·		415/213.1	
1	US	19970311	Enhanced flow	165/80.3	165/122;	Anderson;
	5609202		distributor for		165/124;	Timothy M.
	A .		integrated circuit		165/126;	et al.
	·	· .	spot coolers		165/185;	
			·		165/96;	
					174/16.3;	
			·		257/722;	*
			•		257/E23.099;	
1	TIO	10070211	E 1 10	165/00.2	361/697	A . 1
1	US 5600201	19970311	Enhanced flow	165/80.3	165/122;	Anderson;
	5609201		distributor for		165/124; 165/126;	Timothy M. et al.
	A		integrated circuit spot coolers		165/126;	ctal.
			spot coolers		165/96;	
			•		174/16.3;	
1		i e	i .	ı	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	ı İ

٠.								
						361/697		
	1	US	19970218	Multiple parallel	361/703	165/908;	Chrysler;	
	İ	5604665		impingement		257/722;	Gregory M.	
		Α ·		flow cooling with		361/719	et al.	
				tuning				
	1	US	19960109	Convertible heat	165/137	165/122;	Agonafer;	
		5482113		exchanger for air	:	165/157	Dereje et al.	
		A		or water cooling				
				of electronic				
				circuit				
		l .		components and				
	_	7.70	10051010	the like	60/0.7	126/204	C1 1	
	1	US	19951010	Thermoelectric	62/3.7	136/204;	Chrysler;	
		5456081		cooling assembly		165/185;	Gregory M.	
		A	•	with optimized fin structure for		165/80.2; 257/E23.082;	et al.	
				improved		62/259.2		
			·	thermal		02/239.2		
				performance and				
				manufacturability				
	1	US	19950502	Local	361/700	165/104.26;	Anderson;	
		5412536		condensation		165/80.5;	Timothy M.	
•		Α		control for liquid		174/15.2;	et al.	
				impingement		257/715;		
				two-phase		257/E23.088		
				cooling	•			
	1	US	19941206	Convertible	165/137	165/185;	Agonafer;	
		5370178		cooling module		165/80.3;	Dereje et al.	
		A		for air or water	·	165/80.4;	,	
				cooling of		257/E23.098;		
				electronic circuit		257/E23.099;		
		·		components		361/697; 361/699;		
						361/703		
	1	US ·	19940419	Electronics	62/6		Chrysler	
	1	5303555	177 <del>4</del> 0417 	package with	02/0	257/E23.094; 257/E23.099;	Chrysler; Gregory M.	
•		A		improved		60/520;	et al.	
		1.		thermal		62/259.2	,	
				management by		02.207.2		
				thermoacoustic				
		•	٠	heat pumping				
	1	US	19900522	Circuit module	361/700	257/E23.088;	Chrysler;	
		4928207		with direct liquid		257/E23.093;	Gregory et	
		Α		cooling by a		257/E23.094;	al.	
•				coolant flowing		361/703		
	l			between a heat			1	

	,		producing component and the face of a piston			
1	US 4765397 A	19880823	Immersion cooled circuit module with improved fins	165/104.33	165/146; 165/80.3; 165/80.4; 165/903; 257/E23.098; 361/699; 361/703	Chrysler; Gregory M. et al.

.

.